# **MICROWAVE POWER GaAs FET**

### **High Power GaAs FETs (L, S-Band)**

#### **Features**

- High power
  - $P_{1dB} = 44.5 \text{ dBm at } 1.8 \text{ GHz}$
- High gain
- G<sub>1dB</sub> = 12 dB at 1.8 GHz
  Partially matched type
- Hermetically sealed package

### RF Performance Specifications ( $T_a = 25^{\circ}$ C)

Characteristics	Symbol	Condition	Unit	Min.	Тур.	Max
Output Power at 1dB Compression Point	P <sub>1dB</sub>		dBm	43.5	44.5	_
Power Gain at 1dB Compression Point	G <sub>1dB</sub>	V <sub>DS</sub> = 10V f = 1.8 GHz	dB	11.0	12.0	_
Drain Current	I <sub>DS</sub>		Α	_	7.5	9.0
Power Added Efficiency	N <sub>add</sub>		%	_	35	_
Channel-Temperature Rise	$\Delta T_{ch}$	NOTE 1	°C	_	_	80

## Electrical Characteristics (T<sub>a</sub> = 25° C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max
Trans-conductance	gm	V <sub>DS</sub> =3V I <sub>DS</sub> =7.0A	mS	_	6300	-
Pinch-off Voltage	$V_{GSoff}$	V <sub>DS</sub> =3V I <sub>DS</sub> =140mA	V	-1.0	-3.0	-4.0
Saturated Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =3V V <sub>GS</sub> =0V	А	_	20	26
Gate to Source Breakdown Voltage	V <sub>GSO</sub>	I <sub>GS</sub> =-420 μA	V	-5	_	_
Thermal Resistance	R <sub>th (c-c)</sub>	Channel to case	°C/W	_	1.1	1.4

NOTE 1: $\Delta$ Tch = (V<sub>DS</sub> x I<sub>DS</sub> + Pin - P<sub>1dB</sub>) x R<sub>th(c-c)</sub>

The information contained here is subject to change without notice.

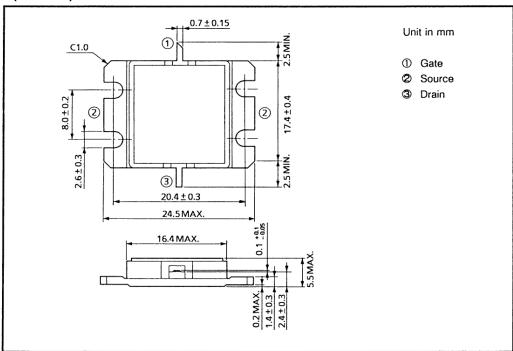
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# Absolute Maximum Ratings ( $T_a = 25^{\circ} C$ )

Characteristic	Symbol	Unit	Rating
Drain Source Voltage	V <sub>DS</sub>	V	15
Gate Source Voltage	V <sub>GS</sub>	V	-5
Drain Current	I <sub>D</sub>	А	20
Total Power Dissipation (Tc = 25°C)	P <sub>T</sub>	W	100
Channel Temperature	T <sub>ch</sub>	°C	175
Storage Temperature	T <sub>stg</sub>	°C	-65~175

### Package Outline (2-16G1B)

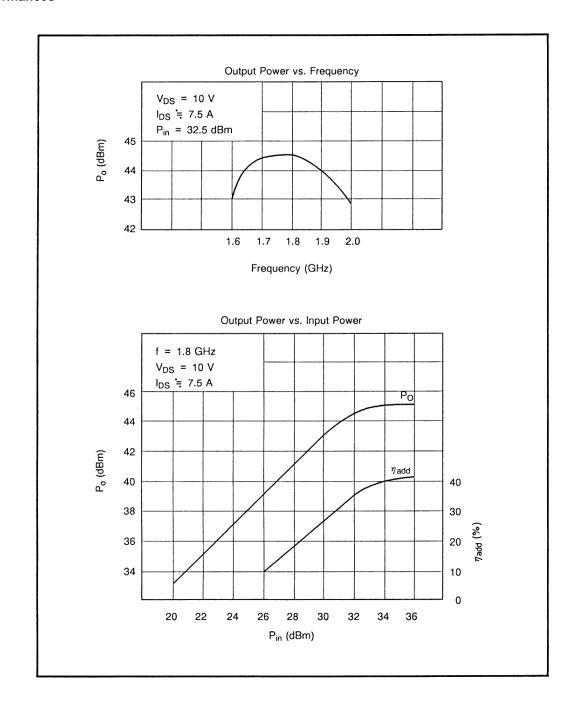


## **Handling Precautions for Packaged Type**

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

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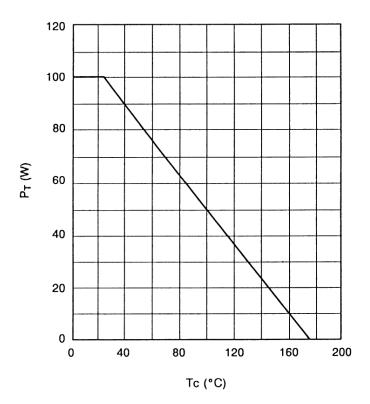
### **RF Performances**



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# **Power Dissipation vs. Case Temperature**



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